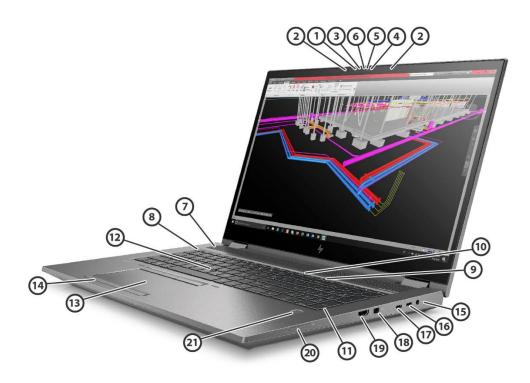
Overview

HP ZBook Fury 17 G7 Mobile Workstation

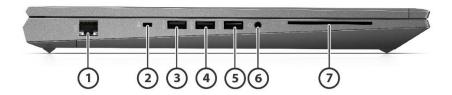


- 1. Ambient Light Sensor
- 2. Internal Microphones (optional)
- 3. Camera LEDs (optional)
- 4. RGB Camera Lens (optional)
- 5. IR Camera LED (optional)
- 6. Camera Cover (optional)
- 7. Speakers with Discrete Amplifier
- 8. Function Keys (changes with configured options)
- 9. Power button
- 10. HP Programmable Key
- 11. Numeric Keypad
- 12. Pointstick

Right

- 13. Touchpad
- 14. 3-button Touchpad
- Indicator LEDs: Power light, Wireless light, Storage usage light
 Power connector
- 16. USB Type-C™ with Thunderbolt™
- 17. USB Type-C™ with Thunderbolt™
- 18. Mini DisplayPort™
- 19. HDMI port
- 20. SD Card Reader
- 21. Fingerprint Sensor (optional)

Overview



Left

- 1. RJ-45
- 2. Nano security lock slot
- 3. USB 3.1 Gen 1 Charging Port

- 4. USB 3.1 Gen 1
- 5. USB 3.1 Gen 1
- 6. Audio Combo Jack
- 7. Smart Card Reader



Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro ¹, powered by HP's collaboration and connectivity technology.
- Accelerate your workflow. Power through projects with up to 128 GB RAM ² for fast rendering, editing and visual effects performance.
- Take multitasking to the next level with the Intel[®] Core[™] i9 processor ³ designed to handle complex, multithreaded apps like Adobe[®] Premier Pro, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.⁴
- Run demanding professional apps with the newest generation Intel® Xeon® processors ⁵ for powerful performance and productivity.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Turing architecture with Quadro® T-Series and RTX graphics; Certified and supported for the apps you use every day.
- Strenuously tested to meet software certification and deliver superb performance with leading software providers, including Autodesk and Adobe® 6.
- Blitz through multiple tasks and ditch external drives with up to 10 TB ^{7,8}, local PCIel NVMe storage up to 21x faster than standard HDD and 6x faster than SATA SSD ⁹.
- Have confidence with the HP's most secure mobile workstations. Instantly protect against visual hacking with HP Sure View ¹⁰, and defend against firmware and malware attacks with HP Sure Start ¹¹ and HP Sure Sense ¹², and have peace of mind with multi-factor authentication- including an infrared camera and fingerprint scanner ¹³.
- Enhanced transfer and upload speeds via dual Thunderbolt™ 3 ports. Get wide-ranging connectivity options to ensure maximum device interaction: USB 3.0, HDMI, mDP, SD card, Smart Card Reader and more.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H ¹⁴ tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 3 ¹⁵ transfers and the flexibility to run up to two external 4K displays ^{16,17}.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges ¹⁸.
- ¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ² Up to 128GB nECC memory is an optional, configurable feature.
- ³ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- ⁴ Adobe Premier Pro and Autodesk 3ds Max sold separately.
- ⁵ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- ⁶ Adobe and Autodesk software sold separately.
- ⁷ For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 3GB (for Windows 10) of system disk is reserved for system recovery software.
- ⁸ 8TB available at launch, 10TB planned to be available September, 2020.
- ⁹ Speeds based on 10TB PCIe NNVMe storage.
- ¹⁰ Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.
- ¹¹ HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- ¹² HP Sure Sense requires Windows 10. See product specifications for availability.
- ¹³ Infrared camera and fingerprint scanner are optional, configurable features.
- ¹⁴ Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.



Overview

NOTE: See important legal disclosures for all listed specs in their respective features sections.



¹⁵ HP Thunderbolt Dock with Thunderbolt[™] 3 sold separately.

¹⁶ External displays sold separately.

¹⁷ Optional hybrid graphics is required to run up to two external 4K displays.

¹⁸ Based on internal testing vs. previous generation product with 802.11ac wireless LAN module.

Features

OPERATING SYSTEM

Preinstalled OS Windows® 10 Pro 64 - HP recommends Windows® 10 Pro for business.1

Windows® 10 Pro for Workstations 641

Windows® 10 Home 641

Windows® 10 Home Single Language 641

FreeDOS 3.0

Web support OS Red Hat® Enterprise Linux® 82

Ubuntu Linux 18.04²

Windows® 10 Enterprise 641

www.intel.com/technology/turboboost for more information.

Supported Version HP tested Windows® 10, version 1809 on this platform. For testing information on newer versions of

Windows® 10, please see: https://support.hp.com/document/c05195282.

PROCESSOR

10th Generation Intel® Xeon® W-10885M vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i9-10885H vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology. 16 MB cache. 8 cores) 1,2,3,4,5,6

10th Generation Intel® Core™ i7-10850H vPro™ with Intel® UHD Graphics (2.7 GHz base frequency, up to 5.1 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores) 1,2,3,4,5,6

10th Generation Intel® Core™ i7 10750H with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)^{1,2,3,4,5}

10th Generation Intel® Core™ i5-10400H vPro™ with Intel® UHD Graphics (2.6 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{1,2,3,4.5,6}

10th Generation Intel® Core™ i5 10300H with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.5 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{1,2,3,4,5}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

⁵ For full Intel® vPro® functionality, Windows, a vPro supported processor, vPro enabled Q370 chipset or higher and vPro enabled WLAN card are required. Some functionality, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for



¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

² For detailed Linux® OS/hardware support information, see: http/www.hp.com/linux_hardware_matrix

Features

Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.



Features

CHIPSET

Mobile Intel® WM 490

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ and Xeon® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. 1,2

GRAPHICS

Integrated

Intel® UHD Graphics 630 1,2,3,4,5

Discrete

NVIDIA Graphic options:

NVIDIA® Quadro® RTX 5000 (16 GB GDDR6 dedicated)1,2,3,4,5

NVIDIA® Quadro® RTX 4000 (8 GB GDDR6 dedicated) 1,2,3,4,5

NVIDIA® Quadro® RTX 3000 (6 GB GDDR6 dedicated)1,2,3,4,5

NVIDIA® Ouadro® T2000 (4 GB GDDR6 dedicated)1,2,3,4,5

NVIDIA® Quadro® T1000 (4 GB GDDR6 dedicated) 1,2,3,4,5

AMD Graphic options:

AMD Radeon Pro W5500M (4 GB GDDR6 dedicated) 1,2,3,4,5

AMD Radeon RX 5500M (4 GB GDDR6 dedicated) 1,2,3,4,5



¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Core™ i9 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™/Core™ i9 with vPro™/XEON® with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

¹ UHD content required to view UHD images.

 $^{^{2}}$ Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

³ HDMI cable Sold Separately

⁴ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁵ miniDP cable sold separately.

⁶ GPU configurations may be limited to specific panel options

Features

DISPLAY

Non-touch

- 17.3" diagonal FHD (1920 x 1080) IPS eDP anti-glare WLED-backlit and ambient light sensor 300 nits 72% CG^{1,2}
- 17.3" diagonal UHD (3840 x 2160) IPS eDP1.4 + PSR2 anti-glare WLED-backlit and ambient light sensor 550 nits 100% DCI-P3^{1,2,3,4}
- 17.3" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 anti-glare WLED-backlit and ambient light sensor 550 nits 100% DCI-P3 Next Gen HP Dream Color display^{1,2,3,4}

Touch

• 17.3" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 550 nits 100% DCI-P3^{1,2,3,4}

HP Virtual Reality Headset (sold separately)

- HP Reverb
- HP Reverb G2



¹ UHD content required to view UHD images.

² Resolutions are dependent upon monitor capability, and resolution and color depth settings.

³ Display options may be limited to specific GPU Configurations.

⁴VESA DisplayHDR 400 certifications are pending.

⁵ Virtual Reality content is required to view Virtual Reality images

Features

STORAGE AND DRIVES*

HDD Storage (SATA 3.2)²

500 GB 7200 rpm SATA FIPS 140-2 SED HDD 500 GB 7200 rpm SATA HDD 1 TB 7200 rpm SATA HDD 2 TB 5400 rpm SATA HDD

M.2 Storage (NVMe™ PCIe SSD)²

256 GB PCIe (NVMe[™]) TLC Self Encrypting (SED) Solid State Drive 512 GB PCIe (NVMe[™]) TLC Self Encrypting (SED) Solid State Drive 256 GB PCIe (NVMe[™]) TLC Solid State Drive 512 GB PCIe (NVMe[™]) TLC Solid State Drive 1 TB PCIe (NVMe[™]) TLC Solid State Drive³ 2 TB PCIe (NVMe[™]) TLC Solid State Drive³ 4 TB PCIe (NVMe[™]) TLC Solid State Drive¹

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)
RAID:

PCIe Gen 3 x 4 lanes NVMe Solid State Drive RAID 0 and RAID 1 support¹

¹ Support only available with 1TB + 1TB M.2 storage or 2TB + 2TB M.2 storage combinations

MEMORY

Maximum Memory^{3,2,5}

128 GB DDR4-2667 non-ECC SDRAM 64 GB DDR4-2667 ECC SDRAM 4 DDR4 SODIMMS⁴ Supports Dual Channel Memory¹ Slots are customer accessible / upgradeable



¹4TB PCIe Gen 3 x4 NVMe M.2 SSD TLC Option will be available by end of 2020. 4TB can only be assigned to storage slot 2.

²Storage slot 2 can only support NVMe only

³Only storage slots 1-3 can support RAID

^{*} For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

¹Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

² Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

³Transfer rates up to 2667 MT/s for nECC and ECC memory combinations when memory suppliers are consistent. If suppliers are not consistent, speeds may drop to 2133 MT/s for nECC and 2400 MT/s for ECC memory combinations. A custom configuration including part number AY104AV can be used to lock in a consistent vendor.

⁴ Intel[®] allows architectures designed with four DIMM slots to run at 2400 MT/s

⁵ Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

Features

NETWORKING/COMMUNICATIONS

I AN

Intel® I219-LM GbE, vPro™
Intel® I219-V GbE, non-vPro™

¹GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro^{™ 1}
Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro^{™ 1}

¹Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

WWAN1

Intel® XMM™ 7360 LTE Advanced CAT 9

¹ WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone dual array digital microphone¹, functions keys for volume up and down, combo microphone/headphone jack, HD audio

¹Dual-microphone array when equipped with optional webcam and optional world facing microphone.

Camera^{1, 2, 3}

720p HD webcam with IR 720p HD webcam



¹ FHD and HD content required to view HD images respectively.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

³Camera-configured options come with a Privacy Shutter

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Kevboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, a Programmable Key, with sperate numeric keypad, HP DuraKey, touchpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices

Dual pointstick; Touchpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: http://www.hp.com/go/isv

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will quide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: http://www.hp.com/go/performanceadvisor

Software

Bing search for IE11

Buy Office

HP Hotkey Support

HP Image Assistant

HP Noise Cancellation Software

HP Performance Advisor8

HP Sure Recover

HP ZCentral Remote Boost²

HP Support Assistant 1,7

Native Miracast support 4

HP Connection Optimizer9

HP Cloud Recovery

myHP

Security Management

Absolute persistence module 6

HP Admin

HP Device Access Manager

HP FingerPrint Sensor

HP Manageability Integration Kit Gen4¹¹

HP Power On Authentication

Security lock slot12

Trusted Platform Module TPM 2.0 Embedded Security Chip with Windows 10 (Common Criteria EAL4+ Certified) (FIPS 140-2

Level 2 Certified)

Master Boot Record security

Pre-boot authentication

Windows Defender¹⁰

HP Client Security Manager Gen5¹⁶

HP BIOSphere Gen6 5

HP Sure Recover Gen3¹³

HP Sure Start Gen6 5, 14



Features

HP Secure Erase ¹⁵
HP Sure Sense¹⁷
HP Secure Platform¹⁸
HP Sure Click
HP Sure Run Gen3

Smartcard Reader - Alcor AU9560 (FIPS 201 Compliant)

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- ¹ HP Support Assistant Requires Windows and Internet Access.
- ² HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.
- ⁴ Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast.
- ⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- ⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:
- http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- ⁸ HP Performance Advisor Software HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html ⁹ HP Connection Optimizer requires Windows 10.
- ¹⁰ Microsoft Defender Opt in and internet connection required for updates.
- 11 HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- ¹² Nano Security lock slot is Lock sold separately.
- ¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. Youmust back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
- ¹⁴ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.
- ¹⁵ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- ¹⁶ HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
- ¹⁷ HP Sure Sense requires Windows 10. See product specifications for availability.
- ¹⁸ Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.



Features

POWER

Power Supply

Up to 15 hours 45 minutes1

HP Long Life 8-cell, 94 Wh Li-ion polymer²

120 W Slim Smart external AC power adapter 150 W Slim Smart external AC power adapter 200 W UltraSlim Smart external AC power adapter

120 W power adapter is configurable with Intel UMA graphics

150 W power adapter is configurable with NVIDIA Quadro T1000 and T2000 configurations

200 W power adapter is configurable with NVIDIA Quadro RTX 3000 or higher configurations

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® 2.0 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country. 1

Low halogen²



¹ Measured with MobileMark 14

² Battery is internal and not replaceable by customer. Serviceable by warranty. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year.

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h) 39.84 x 26.71 x 2.69 cm 15.69 x 10.52 x 1.06 in

Weights

Starting at 2.76kg (6.08 lb)

Weight varies by configuration and components.

A deck: Anodized Aluminum

B deck: Aluminum with plastic antenna cover; Touch has Corning® Gorilla® Glass 5

C deck: Anodized Aluminum D deck: Magnesium Die Cast E door: Magnesium Die Cast

Metal Alloy Hinges

PORTS/SLOTS

1 smart card reader 1 SD 4.0 Media Card Reader

Left side⁶

1 RJ-45

1 USB 3.1 Gen 1 (charging)

2 USB 3.1 Gen 1

1 headphone/microphone combo

Right side⁶

1 power connector 2 USB Type-C™ (Thunderbolt™ 3, pass through support DispalyPort™ 1.4², USB 3.1 Gen 2, with BC 1.2) 1 Mini DisplayPort™ 1.4 1 HDMI 2.0b^{1,3,4,5}

- ¹ HDMI port-cable not included.
- ² Mini DisplayPort 1.4 with discrete, 1.2 with UMA.
- ³ HDMI 2.0b with discrete, 1.4 with UMA.
- ⁴ When both USB Type-C[™] are in use, HDMI cannot be detected
- ⁵ When one USB Type-C™ is in use, HDMI can be detected if USB Type-C™ in use is assigned to different channel
- ⁶ When product is under heavy power loading, performance may be reduced to prevent battery drain. Disconnecting USB devices will restore system performance

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are



Features

governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power **Nominal Operating** 19.5V

Requirements (AC Power) Voltage

Average Operating System in idle mode + max panel Adapter Safety test condition

Power(idle) brightness

Discrete Graphics 80W **Max Operating Power** <200W

41° to 122° F (5° to 50° C) (reading optical) **Temperature Operating**

'41° to 113° F (5° to 45° C) (writing optical)

-40° to 140° F (-40° to 60° C) Non-operating **Relative Humidity Operating** 10% to 90%, non-condensing

> **Non-operating** 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine **Non-operating** 200 G, 2 ms, half-sine

Random Vibration Operating 0.75 grms Non-operating 1.50 grms

Maximum Altitude (unpressurized)

Planned Industry Standard Certifications

Operating -50 to 10,000 ft. (-15.24 to 3,048 m) **Non-operating** -50 to 15,000 ft. (-15.24 to 12,192 m)

UL Yes **CSA** Yes **FCC Compliance** Yes **ENERGY STAR®** Yes **EPEAT®** Yes **ICES** Yes Australia / NZ A-Tick Yes Compliance

CCC Yes Japan VCCI Compliance Yes KCC Yes **BSMI** Yes **CE Marking Compliance** Yes MIL STD 810H Yes **BNCI or BELUS** Yes GOST Yes Saudi Arabian Compliance (ICCP) Yes

UKRSERTCOMPUTER

¹Configurations of the HP ZBook Fury 17 G7 that are ENERGY STAR® qualified are identified as HP ZBook Fury 17 G7 ENERGY STAR on HP websites and on http://www.energystar.gov.

Yes



² EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.

Technical Specifications – Displays

DISPLAYS

17.3" diagonal FHD IPS
eDP1.2 anti-glare WLEDbacklit and ambient light
sensor 300 nits 72% CG
(1920 x 1080)

Outline
Active A
Weight
Diagona

 Outline Dimensions (W x H)
 399.95 x 251.01 mm (max)

 Active Area
 381.89 x 214.81 mm

Weight 550 g (max)

Diagonal Size 17.3 inch

Thickness 4.0 mm (max)

Interface eDP 1.2

Panel Technology IPS

Surface Treatment Anti-Glare

Touch Enabled No

Refresh Rate 60 hrz

Touch Enabled No
Refresh Rate 60 hrz
Brightness 300 nits

Pixel Resolution Format 1920 x 1080 (FHD)

Configuration RGB

Backlight LED
PPI 127
Color Gamut Coverage 72% CG
Color Depth 6 bits + Hi FRC
Viewing Angle UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

17.3" diagonal UHD IPS Outline Dimer eDP1.4 + PSR2 anti-glare Active Area WLED-backlit and ambient light sensor 550 nits 100% DCI-P3 (3840 x Diagonal Size 2160)

Outline Dimensions (W x H) 399.95 x 251.01 mm (max)

Active Area 381.89 x 214.81 mm

 Weight
 550 g (max)

 Diagonal Size
 17.3 inch

 Thickness
 4.0 mm (max)

 Interface
 eDP 1.4 + PSR2

Panel Technology IPS
Surface Treatment Anti-Glare

Touch EnabledNoRefresh Rate60 hrzBrightness550 nits

Pixel Resolution Format 3840 x 2160 (UHD)

Configuration RGB

Backlight LED PPI 127

Color Gamut Coverage100% DCI-P3Color Depth6 bits + Hi FRCViewing AngleUWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Displays

Next Gen HP Dream Color Outline Dimensions (W x H) display 17.3" diagonal UHD IPS HDR 400 eDP1.4 + PSR2 anti-glare WLEDbacklit and ambient light Diagonal Size sensor 550 nits 100%

DCI-P3 (3840 x 2160)

398.6 x 253 mm (max) (w/ bracket & PCB)

Active Area 382.12 x 214.94 mm

Weight 550 g (max) 17.3 inch **Thickness** 4.0 mm (max) Interface eDP 1.4 + PSR2

IPS Panel Technology **Surface Treatment** Anti-Glare **Touch Enabled** No

Contrast Ratio 1000:1 (tvp.) **Refresh Rate** 60Hz **Brightness** 550 nits

Pixel Resolution Pitch 3840 x 2160 (UHD)

> **Format RGB**

Backlight LED PPI 254

Color Gamut Coverage 100% DCI-P3 **Color Depth** 8 bits

UWVA 85/85/85/85 Viewing Angle

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

17.3" diagonal UHD IPS HDR 400 eDP1.4 + PSR2 **WLED-backlit touch** screen with Corning® Gorilla® Glass 5 and ambient light sensor 550 Thickness nits 100% DCI-P3 (3840 x Interface 2160)

Outline Dimensions (W x H) 398.6 x 253 mm (max) (w/ bracket & PCB)

Active Area 382.12 x 214.94 mm

Weight 550 g (max) **Diagonal Size** 17.3 inch 4.0 mm (max) eDP 1.4 + PSR2

IPS Panel Technology

Surface Treatment Gorilla Glass 5 with Anti-Glare

Touch Enabled

Contrast Ratio 1000:1 (typ.)

Refresh Rate 60Hz **Brightness** 550 nits

Pixel Resolution Pitch 3840 x 2160 (UHD)

> **Format RGB**

Backlight LED PPI 254

Color Gamut Coverage 100% DCI-P3 **Color Depth** 8 bits

UWVA 85/85/85/85 **Viewing Angle**

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Storage

Capacity

STORAGE AND DRIVES

256GB PCIe NVMe TLC M.2 Form Factor 2280 Solid State Drive

M.2 2280 **Drive Weight** 0.02 lb (10 q) 256GB Generation 1100 **NAND Type** TLC

Height 2.6 mm Max Width 0.87 in (22 mm) Interface ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

> 530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256GB PCIe NVMe TLC M.2 Form Factor 2280 SED Opal 2 Solid **State Drive**

M.2 2280 **Drive Weight** 0.02 lb (10 q) Capacity 256GB Generation 1100 **NAND Type** TLC

Height 2.6 mm Max Width 0.87 in (22 mm) Interface ACS-3. SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

> 530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512GB PCIe NVMe TLC M.2 Form Factor 2280 Solid State Drive

M.2 2280 **Drive Weight** 0.02 lb (10 q) Capacity 512GB Generation 1100 **NAND Type** TLC

Height 2.6 mm Max Width 0.87 in (22 mm) **Interface** ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

> 530 400



Technical Specifications – Storage

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512TB PCIe NVMe TLC M.2 Form Factor 2280 SED Opal 2 Solid Drive Weight State Drive

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 512GB

Generation 1100

NAND Type TLC

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1TB PCIe NVMe TLC M.2 2280 Solid State Drive
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

Capacity 1TB **NAND Type** TLC

Height2.6 mm MaxWidth0.87 in (22 mm)InterfaceACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Available in RAID 1 config Yes

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2TB PCIe NVMe TLC M.2 2280 Solid State Drive
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

Capacity 2TB NAND Type TLC

Height 2.6 mm Max

Technical Specifications – Storage

Width 0.87 in (22 mm)
Interface ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Available in RAID 1 config Yes

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

4TB PCIe NVMe TLC M.2 2280 Solid State Drive Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 2TB NAND Type TLC

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Optain available as out of cycle option

Can only be configured in Secondary Storage slot

500GB SATA 2.5" HDD Form Factor 2.5"

 Drive Weight
 0.02 lb (10 g)

 Capacity
 500GB

 Generation
 1100

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM: TRIM: DEVSLP

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.



Technical Specifications – Storage

500GB SATA 2.5" SED HDD - FIPS-140-2 Form Factor 2.5"

Drive Weight 0.02 lb (10 g)
Capacity 500GB
Generation 1100
Height 2.6 mm Max
Width 0.87 in (22 mm)
Interface ACS-3. SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1TB SATA 2.5" HDD

Form Factor 2.5"

Drive Weight 0.02 lb (10 g)

Capacity 1TB
Generation 1100
Height 2.6 mm Max
Width 0.87 in (22 mm)
Interface ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2TB SATA 2.5" HDD

Form Factor 2.5"

Drive Weight 0.02 lb (10 g)

Capacity 2TB **Generation** 1100

Height2.6 mm MaxWidth0.87 in (22 mm)InterfaceACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP



HP ZBook Fury 17 G7 Mobile Workstation

QuickSpecs

Technical Specifications – Storage

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel i219LM 10/100/1000 Integrated NIC **Connector** RJ-45

System Interface PCI(Intel proprietary) + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Power consumption Cable Disconnetion: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

Power ACPI compliant – multiple power modes

Management Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface

Auto MDI/MDIX Crossover cable detection

IT Manageability

Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

Intel i219v 10/100/1000 Connector Integrated NIC System Int

Connector RJ-45

System Interface PCI(Intel proprietary) + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support



Technical Specifications – Networking

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Power consumption Cable Disconnetion: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

Power ACPI compliant – multiple power modes

Management Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

RFID Reader Gen 2 (optional) (Rhode)

Dimensions (L x W

x H) Module 50 mm by 23 mm by 2.89 mm **Chipset** SiM3U156+SiM3U154+AMS3911

System interface USB 2.0

System interface (I/O) Audio signal output on card read

NFC RF standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 13033 ISO/IEC 18092 ECMA-340 NFCIP-1

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4 in reading CSN

Reader Mode 13.56MHz:

ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa Topaz cards HID iClass ISO 125kHz: HID Prox UID AWID UID



Technical Specifications – Networking

CASI-RUSCO UID EM 410x UID

Indana ASP/ASP+ UID

Frequency 13.56MHz and 125kHz

NFC Modes Supported Reader

Raw RF Data Rates 106, 212 kbps

Operating

temperature -30°C to 70°C Storage temperature -40°C to 80°C

Humidity 10-90% operating

5-95% non-operating

Supply Operating

voltage 4.35 to 5.25 Volts

Power Consumption Mode Power Consumption, Typical

Polling 75mA Comunication 85mA

Antenna 13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin

connector FPC.

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, nonvPro, supporting gigabit file transfer speeds) non-vPro

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h

IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability Wi-Fi certified Frequency Band 802.11b/g/n/ax

2.402 – 2.482 GHz
802.11a/n/ac/ax
4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz

& 160MHz)

Technical Specifications – Networking

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/q

mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power²
• 802.11b: +18.5dBm minimum
• 802.11g: +17.5dBm minimum

• 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
 802.11n HT40(2.4GHz): +14.5dBm minimum

802.11n HT20(5GHz): +15.5dBm minimum
 802.11n HT40(5GHz): +14.5dBm minimum

• 802.11ac VHT80(5GHz): +11.5dBm minimum

802.11ac VHT160(5GHz): +11.5dBm minimum
 802.11ax HT40(2.4GHz): +10dBm minimum

• 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

• Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps : -93.5dBm maximum

•802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum

802.11n, MCS07 : -67dBm maximum
802.11n, MCS15 : -64dBm maximum

• 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum

•802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Technical Specifications – Networking

Weight 1. Type 2230 : 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber - Radio Off; LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy : 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power ManagementETS 300 328, ETS 300 826CertificationsLow Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 —Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications – Networking

Wireless LAN Standards Intel Wi-Fi 6 AX201 + IEEE 802.11a BT5 (802.11ax 2x2. IEEE 802.11b vPro, supporting gigabit IEEE 802.11g file transfer speeds) IEEE 802.11n **vPro** IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v Interoperability Wi-Fi certified **Frequency Band** 802.11b/g/n/ax • 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 – 5.725 GHz • 5.825 - 5.850 GHz **Data Rates** • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) Modulation Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM Security¹ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification • IEEE 802.11i WAPI **Network Architecture** Ad-hoc (Peer to Peer) Models Infrastructure (Access Point Required) Roaming IEEE 802.11 compliant roaming between access points Output Power² • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
 802.11n HT40(2.4GHz): +14.5dBm minimum
 802.11n HT20(5GHz): +15.5dBm minimum
 802.11n HT40(5GHz): +14.5dBm minimum

Technical Specifications – Networking

802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode :2.0 W

• Receive mode: 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode :50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum
802.11ax, MCS11(HT40): -59dBm maximum
802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

cara to support WEAR Pill-10 Communications and bluetoot

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230 : 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber - Radio OFF; LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy : 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)



Technical Specifications – Networking

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 —Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

Intel® XMM™ 7360 LTE-Advanced CAT9 (Pandora)*

Technology/Operating

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100

(Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

 ${\tt 3GPP\,Release\,11\,LTE\,Specification\,CAT.9,\,DL\,60MHz\,BW\,throughput\,up\,to\,450Mbps;\,UL\,20MHz}$

throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Technical Specifications – Networking

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

on all products or in all countries.

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available

Near Field Communications Controller (optional)

Dimensions (LxW

x H) Module 25 mm by 10 mm by 2.0 mm

Chipset NPC100 System interface 12C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support

Reader (PCD-VCD) ISC

Mode(1)

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC- ISO/IEC 14443 A

VICC) Mode(1)

SO/IEC 14443 A

ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer Raw RF Data Rates 106, 212, 424, 848 kbps

Operating

temperature 0°C to 70°C

Storage temperature -20°C to 125°C

Humidity 10-90% operating

5-95% non-operating



Technical Specifications - Networking

Supply Operating

voltage 4.35 to 5.25 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption Booster enable,

VCC_BOOST = 5V) Polling
Mode Power Detecte
Consumption, Tag Typ
Typical

VBAT= 3.3V,

Polling 7.3 mA

Detected Test Tag Type 1 Net Module 236.8 mA

Detected Test Total 288.8 mA

Tag Type 2 Net Module 241.8 mA

Detected TestTotal 287.7 mATag Type 3Net Module 240.7 mADetected TestTotal 282.3 mATag Type 4Net Module 235.3 mA

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.



Technical Specifications – Power

POWER

120 Watt Slim Smart AC Adapter
 Dimensions
 138x68.5x25.4mm

 Weight
 unit: 350g +/- 10g

Input Input Efficiency 88% at 115 Vac and 89% at 230Vac

Input frequency 47 ~ 63 Hz

range

Input AC current 1.7 A at 90 Vac and Maximum Load

Output Output power 120W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <18.0A

Connector C14

Environmental Design Operating

temperature

32° to 95° F (0° to 35° C)

Non-operating

(storage) temperature -4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity5% to 95%Storage Humidity5% to 95%

EMI and Safety Certifications Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

150 Watt Slim Smart AC Adapter

 Dimensions
 138x66x22mm

 Weight
 unit: 325g +/- 10g

Input Efficiency 88% at 115 Vac and 89% at 230 Vac

Input frequency 47 ~ 63 Hz

range

Input AC current 2.7 A at 90 Vac and Maximum Load

Output Output power 150W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <16.0A

Connector C14

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature



^{*}Can only be configured with Intel UMA Graphics option

Technical Specifications – Power

Non-operating -4° to 185° F (-20° to 85° C)

(storage) temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

*Can only be configured with Quadro T1000 and T2000 Graphics option

200 Watt UltraSlim Smart AC Adapter

 Dimensions
 152x73x23.5mm

 Weight
 unit: 530g +/- 10g

Input Input Efficiency 88% at 115 Vac and 89% at 230Vac

Input frequency range 47 ~ 63 Hz

Input AC current 2.9 A at 90 Vac and Maximum Load

Output Output power 200W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <16.0A

Connector C14

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Eg

Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

*Can only be configured with Quadro RTX3000, RTX4000, RTX5000 Graphics and Radeon W5500M, RX 5500M Graphics option



Technical Specifications – Power

HP Long Life 8-cell Polymer (94Wh) Battery **Cells/Type** 8 cell

Energy Voltage 11.55V

Amp-hour capacity 4.15Ah

Temperature Operating (Charging) 0° to 60° C

Operating (Discharging) -20° to 70° C

Fuel Gauge LED NA

Warranty Depends on system offering

Optional Travel Battery N

Available

Refer to http://www.hp.com/support/batterywarranty/ for battery warranty information.



^{*} Batteries have a default one year limited warranty except for Long Life batteries which will have same1-year or 3-year limited warranty as the platform.

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test method)

STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	9.95 W	10.02 W	9.92 W	
Normal Operation (Long idle)	6.08 W	6.21 W	6.06 W	
Sleep	1.61 W	1.68 W	1.54 W	
Off	0.437 W	0.46 W	0.40 W	

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	34.03 BTU/hr	34.27 BTU/hr	33.93 BTU/hr
Normal Operation (Long idle)	20.79 BTU/hr	21.24 BTU/hr	20.73 BTU/hr
Sleep	5.51 BTU/hr	5.75 BTU/hr	5.27 BTU/hr
Off	1.49 BTU/hr	1.57 BTU/hr	1.37 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	2.6	16	
Fixed Disk – Random writes	3.7	22	
Optical Drive – Sequential reads	2.9	17.4	

Longevity and Upgrading

"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- AC Adapter
- Battery
- WLAN/WWAN module
- 4 storage slots (M.2 and HDD)
- 4 SODIMM memory slots



Technical Specifications - Environmental

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Battery description: 6-cell high capacity Lithium-Ion battery (optional 8 cell available)

Battery type:

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 10.08% post-consumer recycled plastic (by wt.)
- This product is 94.2% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	0.375 g
	PAPER/Molded Pulp	0.202 g
Internal:	PLASTIC/Polyethylene low density - LDPE	0.012 g
	PLASTIC/Polypropylene - PP	0.005 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 12.6 recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Technical Specifications – Environmental

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.



Technical Specifications – Environmental

These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Displays	HP Z32 31.5" 4k UHD Display	1AA81A8#XXX
	HP Z38c 37.5" Curved Display	Z4W65A8#XXX
6 222	LID Dusinger Pools and (up to 17.7%)	25.557.4.4
Case	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Slim Top Load (up to 17.3")	2UW02AA
	HP Exec 17.3 Midnight Backpack (Caterpillar Jr)	1KM17AA
Docking	HP Adjustable Dual Monitor Stand	AW664AA
Accessories	HP Adjustable Display Stand	AW663AA
	HP Display and Notebook Stand II	E8G00AA
	HP Monitor Stand	M9X76AA
	HP Dual Hinge II Notebook Stand	E8F99AA
	HP Hot Desk Stand (up to 32" monitor)	W3Z73AA
	HP Hot Desk Stand Monitor Arm (for use with W3Z73AA; supports two 24" monitors	W3Z74AA
	HP TB Audio Module (comp with Hook dock)	3AQ21AA
	HP TB Dock G2 Combo Cable (this is 230W) comp with Hook dock	3XB96AA
Docking station	HP USB-C Mini Dock - power not supported on mWKS	1PM64AA
	HP TB Dock G2 w/ Combo Cable (Hook) (this is 230W)	3TR87AA
	HP USB-C/A Universal Dock G2 (Adicora-D) Power Not Supported on Mobile Workstations	5TW13AA
	HP USB-C Dock G5 (Adicora-A) Power Not Supported on Mobile Workstations	5TW10AA
Input/Output -	HP Comfort Grip Wireless Mouse (Alvin) (See Link 5 Tab)	H2L63AA
Mice	HP 3-button USB Laser Mouse (Apollo)	H4B81AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP USB Travel Mouse (Beethoven)	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
	HP Elite Presenter Mouse	2CE30AA
Imput/Out-ut	LID Clim LICD Keyboord and Mours	TCT03.4.4
Input/Output - Keyboard	HP Slim USB Keyboard and Mouse	T6T83AA
ncyoouru	HP Slim Wireless Keyboard and Mouse	T6L04AA
Input/Output -	HP USB-C to USB-A Hub (Jake)	Z6A00AA
Adapter	HDMI to VGA Adapter	H4F02AA
	HP HDMI to DVI Adapter	F5A28AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA
	HP Single miniDP-to-DP Adapter Cable	2MY05AA
Collaboration	HP UC Wired Headset	K7V17AA



Options and Accessories (sold separately and availability may vary by country)

Memory	HP 8GB 2666Mhz DDR4	4VN06AA
	HP 16GB 2666Mhz DDR4	4VN07AA
	HP 32GB 2666MHz DDR4	6NX83AA
	HP 8GB 2666MHz DDR4 ECC	4UY11AA
	HP 16GB 2666MHz DDR4 ECC	4UY12AA
Power - A/C	HP 200W Smart AC Adapter (4.5mm) (Pecan)	
Adapter	HP 200W Smart AC Adapter (4.5mm) (Eris)	
Adapter Dongle	HP 7.4mm to 4.5mm DC Dongle	K0Q39AA
Security	HP Essential Combination Lock (Herb)	TOY16AA
	HP Keyed Cable Lock 10mm (Wolv II)	T1A62AA
	HP Dual Head Keyed Cable Lock (Sumo)	T1A64AA
Storage - Externa	HP External USB DVDRW Drive	F2B56AA
Storage - SS M2	HP 256GB PCIe 3x4 NVMe SSD (2280)	V3K66AA
	HP 512GB PCIe 3x4 NVMe DS SSD (2280)	V3K67AA



Copyright © 2020 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core, and Celeron, Thunderbolt and vPro are registered trademarks or trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor used by HP Inc. under license. AMD, FirePro, and Enduro are trademarks of Advanced Micro Devices, Inc. Adobe is a trademark of Adobe Systems Incorporated. Microsoft and Windows are U.S. registered trademarks of Microsoft Corporation in the United States and/or other countries. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. SD, SDHC, and SDXC are trademarks or registered trademarks of SD-3C in the United States, other countries or both. USB Type-C and USB-C are trademarks of USB Implementers Forum. ENERGY STAR® is a registered trademark mark of the U.S. Environmental Protection Agency.

Date of change:	Version History:		Description of change:
September 11, 2020	From v1 to v2	Changed	Format

